



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-04-15
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LD39050PU33R	MYYG*UA11AC5	A	SA1A	2014-04-15
Amount		UoM	Unit type	ST ECOPACK Grade
24.421		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3X3X0.95	6	No lead	
Comment	Package: VDFPN 6 3X3 0,95 PITCH			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MYG*UA11ACS					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other Inorganic Material	0.441	mg	Supplier	Silicon Die	Silicone (Si)	7440-21-3		0.418	mg	947846	17116
Silicon Die			mg	Supplier	Metallization	Aluminium (Al)	7429-90-5		0.005	mg	11338	205
Silicon Die			mg	Supplier	Metallization	Tungsten (W)	7440-33-7		0.004	mg	9070	164
Silicon Die			mg	Supplier	Passivation	Silicon Nitride (SiN)	68034-42-4		0.001	mg	2268	41
Silicon Die			mg	Supplier	Passivation	Silicon Oxide(SiO2)	7631-86-9		0.009	mg	20408	369
Silicon Die			mg	Supplier	Passivation	Gamma-butyrolactone	96-48-0		0.003	mg	6803	123
Silicon Die			mg	Supplier	Passivation	Polyhydroxyamide	55295-98-2		0.001	mg	2268	41
Leadframe	Copper and its alloy	9.03	mg	Supplier	Alloy	Copper	7440-50-8		8.722	mg	965891	357152
Leadframe			mg	Supplier	Alloy	Iron	7439-89-6		0.204	mg	22591	8353
Leadframe			mg	Supplier	Alloy	Lead	7439-92-1		0.001	mg	111	41
Leadframe			mg	Supplier	Alloy	Phosphorus	7723-14-0		0.002	mg	221	82
Leadframe			mg	Supplier	Alloy	Zinc	7440-66-6		0.011	mg	1218	450
Leadframe			mg	Supplier	Alloy	Silver	7440-22-4		0.09	mg	9967	3685
Die Attach	Other Organic Material	0.14	mg	Supplier	Glue	Silver	7440-22-4		0.113	mg	807143	4627
Die Attach			mg	Supplier	Glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.014	mg	100000	573
Die Attach			mg	Supplier	Glue	methylene diacrylate	42594-17-2		0.004	mg	28571	164
Die Attach			mg	Supplier	Glue	Dicyclopentenyloxyethyl methacrylate	68586-19-6		0.004	mg	28571	164
Die Attach			mg	Supplier	Glue	Palladium (Pd)	7440-05-3		0.004	mg	28571	164
Die Attach			mg	Supplier	Glue	Dicumyl peroxide	80-43-3		0.001	mg	7143	41
Bonding Wire	Other Inorganic Material	0.19	mg	Supplier	Bonding Wire	Au	7440-57-5		0.19	mg	1000000	7780
Encapsulation	Other Organic Material	14	mg	Supplier	Molding Compound	Fused Silica	60676-86-0		13.118	mg	937000	537161
Encapsulation			mg	Supplier	Molding Compound	epoxy resin	85954-11-6		0.42	mg	30000	17198
Encapsulation			mg	Supplier	Molding Compound	phenol resin	26834-02-6		0.42	mg	30000	17198
Encapsulation			mg	Supplier	Molding Compound	carbon black	1333-86-4		0.042	mg	3000	1720
Finishing	Other Inorganic Material	0.62	mg	Supplier	Connection coating	Sn	7440-31-5		0.62	mg	1000000	25388